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Date

May 20, 2002

Stephanie Jansen

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Salman Akram; Alan G. Wood; and Attorney Docket No.: 500185.03
Warren M. Farnworth
Serial No. : 09/631,900 Group Art Unit : 2827
Filed : August 4, 2000 Examiner : Lourdes C. Cruz
Title : APPARATUS AND METHODS OF TESTING AND ASSEMBLING BUMPS
DEVICES USING AN ANISOTROPICALLY CONDUCTIVE LAYER

TECHNOLOGY CENTER 2800

JUN 11 2002

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Box Non-Fee Amendment
Commissioner of Patents
Washington, DC 20231

AMENDMENT

Sir:

Applicants acknowledge receipt of the Office Action dated May 7, 2002.

In the Claims:

Please amend claim 12 as follows:

B/ 12. (Amended) The apparatus of claim 9 wherein the anisotropically conductive layer comprises an anisotropically conductive paste, the conductive bumps being at least partially embeddable within the paste.

REMARKS

In the communication dated May 7, 2002, Examiner Talbot stated that the reply filed on February 13, 2002 was not fully responsive because it did not respond to the § 112, second paragraph rejections as set forth in the previous Office Action. Upon review, Applicants' acknowledge that the Remarks included in the response of February 13, 2002, did not amend claim 12 or affirmatively discuss why the rejection of claim 8 under § 112, second paragraph was not appropriate. That rejection of claim 8 was based on lack of antecedent basis for "the corresponding one contact pad" and the rejection of claim 12 was for lack of antecedent basis for "the solder bumps".

The undersigned attorney disagrees with the rejection of claim 8 on this ground. Claim 8 depends from claim 7, which depends from claim 1. Claim 1 introduces "a corresponding one of the contact pads." Therefore, there is proper antecedent basis for this element in claim 8.

Claim 12 has been amended to replace "solder" with --conductive-- in reference to the bump, which makes claim 12 refer to the "conductive bumps" recited in base claim 9, thereby giving this element proper antecedent basis.

The Interview Summary attached with the communication of May 7, 2002, also indicated that the formal written reply to the last Office Action must include a separate summary of the substance of this intervening interview (because the box indicating otherwise was not checked).

In the telephonic interview with Examiner Lourdes, the undersigned attorney confirmed that no amendments to the claims were made in the response of February 13, 2002, but that the undersigned neglected to remove the phrase "in light of the foregoing amendments" in the concluding paragraph. In addition, the undersigned clarified that the arguments set forth in the reply were responsive to the Office Action in that it included specific reference to the claims after a discussion of the disclosed embodiments in the specification. In addition, the undersigned clarified that "embedded solder balls" as mentioned in the Remarks, did not require further discussion with reference to the claims because other items were sufficient to distinguish the claims over the cited art.

Attached hereto is a marked-up version of the changes made to the claims by the current amendment. The attached page is captioned "Version with Markings to Show Changes Made".

All of the claims remaining in the application are now clearly allowable. Favorable consideration and a Notice of Allowance are earnestly solicited.

Respectfully submitted,

DORSEY & WHITNEY LLP



Mark W. Roberts, Ph.D.
Registration No. 46,160

MWR:sj

Enclosures:

Postcard

Fee Transmittal Sheet (+ copy)

1420 Fifth Avenue, Suite 3400
Seattle, WA 98101-4010
(206) 903-8728 (telephone)
(206) 903-8820 (fax)

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